Claims

- [c1] A package and method for packaging optoelectric devices, comprising:
 - a generally rectangular package body comprising four sidewalls:
 - one or more than one thermal electrical cooler; one or more than one platform on which opto-electronic

devices and components to be disposed;

attaching the said thermal electrical cooler(s) on the sidewall(s) of the package box by applying epoxy or solder;

attaching the side(s) of the said platform(s) to the top of the thermal electrical coolers.

- [c2] The package and method of claim 1, wherein the package body has one or more than optical connector on its sidewall(s).
- [c3] The package and method of claim 1, wherein the package body has a top defining a generally rectangular opening and a closed bottom.
- [c4] The package body of claim 3 further comprising a lid hermetically scaled to the top of the package, the lid be-

ing free of connectors, leads, and mounting tabs.

- [05] The package and method of claim 1, wherein the package box defining one generally rectangular top opening and another generally rectangular bottom opening.
- [c6] The package body of claim 5 further comprising a top lid and a bottom lid hermetically scaled to the top and the bottom of the box, the top and bottom lids being free of connectors, leads, and mounting tabs.
- [c7] The package and method of claim 1, wherein the package box is dual in-line package, in which a plurality of electronic leads extend the bottom of the said package.
- [08] The package and method of claim 1, wherein the package box is butterfly box, in which a plurality of electronic leads extend one or more than one sidewall of the said package.
- [c9] The package and method of claim 1, wherein the thermal electrical cooler has a top plate and bottom plate and semiconductor elements sandwiched between the said top and bottom plates.
- [c10] The package and method of claim 1, wherein the package body has no or one or more than one radio-frequency connector on its sidewall(s) for high frequency

connection to or from the component(s) inside the box.